

Abstract of the Disclosure

Disclosed is a laser diode having a PCB type lead frame. In the laser diode, a luminous element functions to emit a laser beam. A frame unit has an upper section mounted with the luminous element and functions to radiate heat generated during creation of the laser beam. A housing has an internal space for receiving the frame unit and an exit hole communicating with the internal space for allowing the laser beam to pass through the same. A Printed Circuit Board (PCB) has a plurality of pattern electrodes formed on an upper face of the PCB, the pattern electrodes being electrically connected with the luminous element. The semiconductor laser diode of the invention has a simple structure to facilitate an assembling process, improve productivity, save manufacturing cost and increase radiating surface area thereby improving heat radiation characteristics. The invention can further prevent a finger of a worker from direct contact with a luminous element when a worker handles components in an assembly line so that precision components are not polluted or damaged.